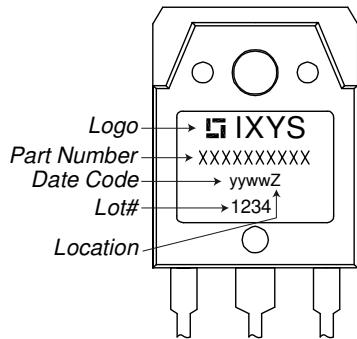


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Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			150	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			150	V
I_R	reverse current, drain current	$V_R = 150 V$ $V_R = 150 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		900 5	μA mA
V_F	forward voltage drop	$I_F = 60 A$ $I_F = 120 A$ $I_F = 60 A$ $I_F = 120 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		0.93 1.13 0.80 1.03	V V
I_{FAV}	average forward current	$T_C = 150^\circ C$ rectangular $d = 0.5$	$T_{VJ} = 175^\circ C$		60	A
V_{F0} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 175^\circ C$		0.51 3.9	V $m\Omega$
R_{thJC}	thermal resistance junction to case				0.4	K/W
R_{thCH}	thermal resistance case to heatsink			0.3		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		375	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}; V_R = 0 V$	$T_{VJ} = 45^\circ C$		1.20	kA
C_J	junction capacitance	$V_R = 24 V$ f = 1 MHz	$T_{VJ} = 25^\circ C$		481	pF

Package TO-3P			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal ¹⁾			70	A
T_{VJ}	virtual junction temperature		-55		175	°C
T_{op}	operation temperature		-55		150	°C
T_{stg}	storage temperature		-55		150	°C
Weight				5		g
M_d	mounting torque		0.8		1.2	Nm
F_c	mounting force with clip		20		120	N

Product Marking



Part description

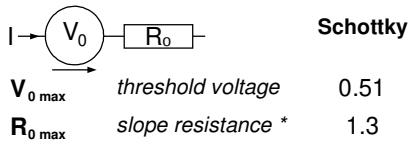
D = Diode
 S = Schottky Diode
 A = low VF
 120 = Current Rating [A]
 C = Common Cathode
 150 = Reverse Voltage [V]
 QB = TO-3P (3)

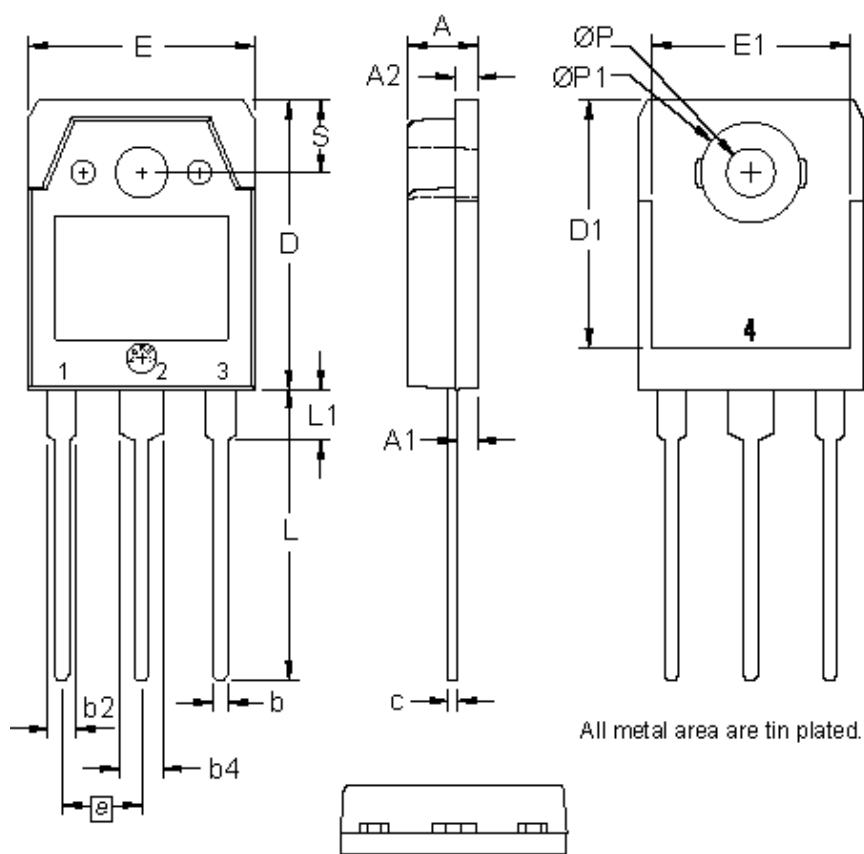
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSA120C150QB	DSA120C150QB	Tube	30	501788

Equivalent Circuits for Simulation

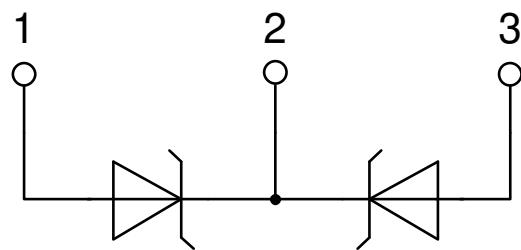
* on die level

$T_{VJ} = 175^\circ\text{C}$



Outlines TO-3P


Dim.	Millimeter		Inches	
	min	max	min	max
A	4.70	4.90	0.185	0.193
A1	1.30	1.50	0.051	0.059
A2	1.45	1.65	0.057	0.065
b	0.90	1.15	0.035	0.045
b2	1.90	2.20	0.075	0.087
b4	2.90	3.20	0.114	0.126
c	0.55	0.80	0.022	0.031
D	19.80	20.10	0.780	0.791
D1	16.90	17.20	0.665	0.677
E	15.50	15.80	0.610	0.622
E1	13.50	13.70	0.531	0.539
e	5.45	BSC	0.215	BSC
L	19.80	20.20	0.780	0.795
L1	3.40	3.60	0.134	0.142
ØP	3.20	3.40	0.126	0.134
ØP1	6.90	7.10	0.272	0.280
S	4.90	5.10	0.193	0.201



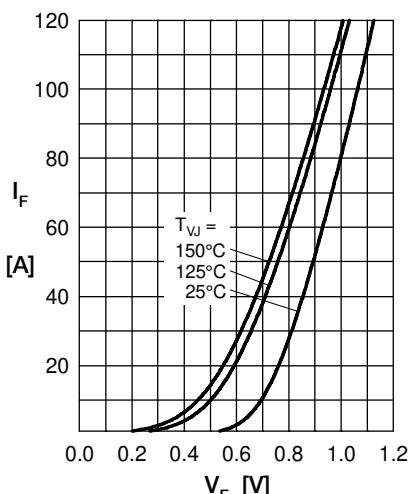
Schottky


Fig. 1 Max. forward voltage drop characteristics

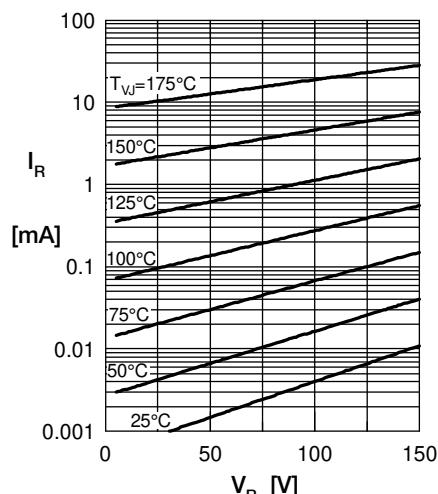


Fig. 2 Typ. reverse current I_R vs. reverse voltage V_R

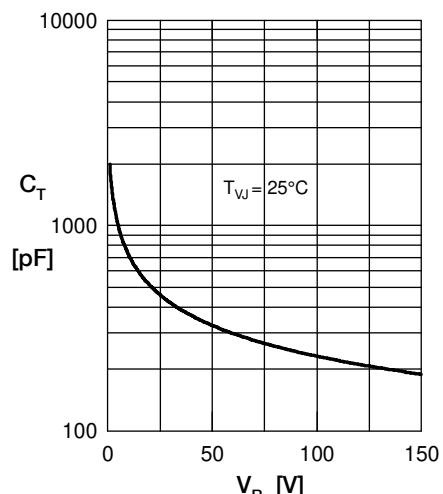


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

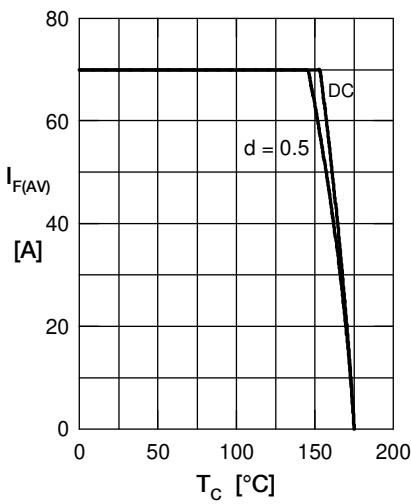


Fig. 4 Average forward current $I_{F(AV)}$ vs. case temp T_C

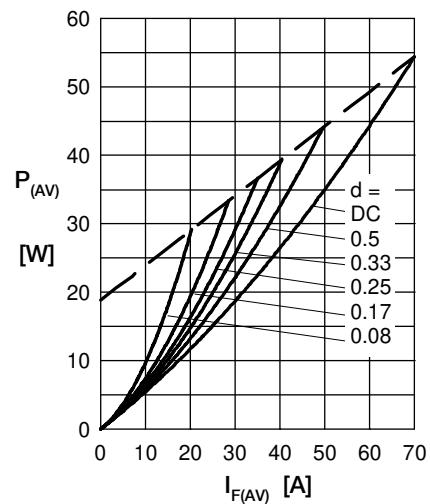


Fig. 5 Forward power loss characteristics

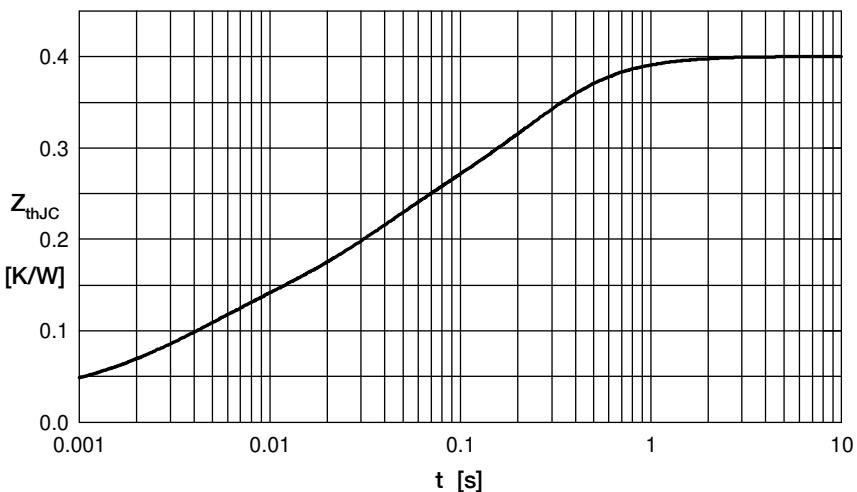


Fig. 6 Transient thermal impedance junction to case at various duty cycles

R_{thi}	t_i
0.022	0.0002
0.082	0.0032
0.104	0.026
0.165	0.208
0.027	0.79

Note: All curves are per diode